

Technical Data Sheet

HELOXY™ Modifier 71

Product Description

HELOXY™ Modifier 71 is an undiluted amber colored, low-viscosity liquid, aliphatic epoxy ester resin that imparts increased flexibility and resistance to thermal shock when blended with conventional liquid bisphenol A based epoxy resins.

Application Areas/Suggested Uses

- Adhesives
- Body solders
- Caulking and sealing compounds
- Electrical casting and encapsulating
- Glass to metal glazing compositions
- Large castings
- Tooling compositions
- Filament winding

Benefits

- A low-viscosity flexibilizer that serves as a viscosity depressing agent.
- A product that improves impact strength and toughness to a conventional liquid bisphenol A epoxy resin.

Sales Specifications

Property	Value	Unit	Test Method
Color	10	Gardner	ASTMD1544
Viscosity at 25°C	400 - 900	cP	ASTMD445
Weight per Epoxide	390 - 470	g/eq	ASTMD1652

Typical Properties

Property	Value	Unit
Density @ 25°C	8.2	lbs/gal
Flash Point	140	°C
Gravity Specific @ 25°C	0.98	
Physical Form	Clear amber liquid	

Accelerators

Another study was undertaken to determine the effect of phenolic accelerators on the properties of HELOXY Modifier 71 systems. Our laboratory determined that a formulator could add up to 5 parts of phenol per 100 parts of HELOXY Modifier 71 with no effect on tensile elongation. Higher levels of phenol decrease tensile strength and exhibit a deleterious effect on chemical resistance.

Cure with Acid Anhydrides

HELOXY Modifier 71
<https://www.hexion.com/en-US/product/heloxymodifier-71>

Generated: May 27, 2022
 Issue Date:
 Revision: 9/1/2007 12:00:00 AM

© and ™ Licensed trademarks of Hexion Inc.

The information provided herein was believed by Hexion Inc. ("Hexion") to be accurate at the time of preparation or prepared from sources believed to be reliable, but it is the responsibility of the user to investigate and understand other pertinent sources of information, to comply with all laws and procedures applicable to the safe handling and use of the product and to determine the suitability of the product for its intended use. All products supplied by Hexion are subject to Hexion's terms and conditions of sale. **HEXION MAKES NO WARRANTY, EXPRESS OR IMPLIED, CONCERNING THE PRODUCT OR THE MERCHANTABILITY OR FITNESS THEREOF FOR ANY PURPOSE OR CONCERNING THE ACCURACY OF ANY INFORMATION PROVIDED BY HEXION**, except that the product shall conform to Hexion's specifications. Nothing contained herein constitutes an offer for the sale of any product.

As with amine curing agents, acid anhydrides can be used with HELOXY Modifier 71 or blends of this resin with EPON Resin 828 to produce tough, flexible polymers. Curing agent accelerators or catalysts, such as EPIKURE Curing Agent 3253 or benzyl dimethylamine (Aceto Corporation), are used to reduce the required cure time and cure temperature. Table 5 displays data on HELOXY Modifier 71 cured with two popular acid anhydrides. Table 6 displays tensile properties of several blends of HELOXY Modifier 71 and EPON Resin 828 cured with NADIC Methyl Anhydride. Again, you will note that adjusting the flexibilizer level in the EPON Resin 828 allows broad latitude in formulating a system with the desired tensile strength and elongation properties.

Cure with Aliphatic Amine Curing Agents

Blends of HELOXY Modifier 71 and EPON Resin 828 cured with aliphatic amines yield a wide range of flexible to semi-rigid polymers. The final properties of these polymers are affected by the type of amine curing agent and the ratio of HELOXY Modifier 71 to EPON Resin 828. Although most of the data presented in this technical bulletin is based on systems cured at elevated temperatures, data is included which show that EPI-CURE Curing Agents 3223 and 3200 are effective room temperature curing agents.

Table 1 illustrates the effect of the type of amine curing agent on tensile properties of several HELOXY Modifier 71/EPON Resin 828 blends cured for 4 hours at 125 °C.

The effect of aging on tensile properties was studied using EPI-CURE Curing Agents 3223 and 3200 at a given ratio of HELOXY Modifier 71 to EPON Resin 828 (75% HELOXY Modifier/ 25% EPON Resin). The results of this study are summarized in Table 2. In this second table, you will note that a more complete cure is achieved when the system is force cured, versus curing at ambient temperatures.

In Table 3, gel times are displayed for various HELOXY Modifier 71 and EPON Resin 828 blends cured with either EPIKURE Curing Agent 3223 or EPIKURE Curing Agent 3200 determined in one quart masses. You will note that either HELOXY Modifier 71 alone or blends of HELOXY Modifier 71 and EPON Resin 828 impart somewhat slower curing than EPON Resin 828, as evidenced by the significantly longer gel times.

Cure with an Aromatic Diamine

In Table 4, data on blends of HELOXY Modifier 71 and EPON Resin 828 cured with ANCAMINE® Z (4,4'-Methylenedianiline), an aromatic diamine, are summarized. You will note a wide range of tensile properties can be achieved depending on the ratio of EPON Resin 828 and HELOXY Modifier 71.

Cure with Lewis Acids

Table 7 compiles tensile properties on a 75/25 by weight blend of HELOXY Modifier 71/ EPON Resin 828, cured with various levels of boron trifluoride monoethylamine. In this study, four parts of boron trifluoride monoethylamine appears to be the optimal level of Lewis acid.

Curing Agents

Blends of HELOXY Modifier 71 and EPON™ Resin 828 can be cured with all curing agents except the polyamine adducts (i.e., EPIKURE™ Curing Agent 3282), which produce incompatible cured products.

Depending upon the ratio of resin blend and the hardener used, the elongation at break can range as high as 200-300%, although 50-100% is more common. The use of HELOXY Modifier 71 as the sole resin in a formulation is not recommended. As in the case of most common flexibilizers, high concentrations of HELOXY Modifier 71 tend to decrease the superior chemical resistance of unmodified epoxy resin systems. Also, experience has shown that optimum tensile properties are normally reached with elevated temperature cures because there is a tendency for room temperature amine cured systems to age harden. Results obtained with various curing agent systems reported in the following sections are intended as a guide when selecting an EPON Resin 828/HELOXY Modifier 71/ EPIKURE Curing Agent system for your specific application.

FDA Status

HELOXY Modifier 71 is not listed under the Code of Federal Regulations (21 CFR); therefore, Hexion cannot recommend its use for food contact applications.

Safety, Storage & Handling

Please refer to the MSDS for the most current Safety and Handling information.

Please refer to the Hexion web site for Shelf Life and recommended Storage information.

CAUTION: Hexion has found that HELOXY Modifier 71 will have a viscosity/epoxide equivalent weight increase of about 10% per month when stored at 30 °C (86 °F). As this occurs, the compatibility with other epoxy resins, such as EPON Resin 828, will decrease. We recommend the product be stored at 13 °C (55 °F), or lower, in order to maintain a reasonable shelf life. Also, the oldest production of HELOXY Modifier 71 should be consumed first. Typical storage/ stability time and temperatures are listed as follows:

HELOXY Modifier 71
<https://www.hexion.com/en-US/product/heloxymodifier-71>

Generated: May 27, 2022
Issue Date:
Revision: 9/1/2007 12:00:00 AM

© and ™ Licensed trademarks of Hexion Inc.

The information provided herein was believed by Hexion Inc. ("Hexion") to be accurate at the time of preparation or prepared from sources believed to be reliable, but it is the responsibility of the user to investigate and understand other pertinent sources of information, to comply with all laws and procedures applicable to the safe handling and use of the product and to determine the suitability of the product for its intended use. All products supplied by Hexion are subject to Hexion's terms and conditions of sale. **HEXION MAKES NO WARRANTY, EXPRESS OR IMPLIED, CONCERNING THE PRODUCT OR THE MERCHANTABILITY OR FITNESS THEREOF FOR ANY PURPOSE OR CONCERNING THE ACCURACY OF ANY INFORMATION PROVIDED BY HEXION**, except that the product shall conform to Hexion's specifications. Nothing contained herein constitutes an offer for the sale of any product.

Storage temperature	Estimated shelf life
55°F	1 year
75°F	5 months
90°F	2 1/2 months
105°F	1 month

It should be noted that, if the product is subjected to excessive heating while compounding, the shelf life could be significantly reduced. Your manufacturing processes should be modified accordingly.

Exposure to these materials should be minimized and avoided, if feasible, through the observance of proper precautions, use of appropriate engineering controls and proper personal protective clothing and equipment, and adherence to proper handling procedures. None of these materials should be used, stored, or transported until the handling precautions and recommendations as stated in the Material Safety Data Sheet (MSDS) for these and all other products being used are understood by all persons who will work with them. Questions and requests for information on Hexion Inc. ("Hexion") products should be directed to your Hexion sales representative, or the nearest Hexion sales office. Information and MSDSs on non-Hexion products should be obtained from the respective manufacturer.

Packaging

Available in bulk and drum quantities.

Contact Information

For product prices, availability, or order placement, please contact customer service:

www.hexion.com/Contacts/

For literature and technical assistance, visit our website at www.hexion.com